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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



Applicant: Susan J. Boon

Title: METHOD OF PACKAGING AT A WAFER LEVEL

Docket No.: 303.601US3

Filed: November 26, 2003

Examiner: James M. Mitchell

Serial No.: 10/722,838

Due Date: February 7, 2005

Group Art Unit: 2814

Mail Stop Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

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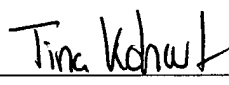
- ☒ A return postcard.
- ☒ A Response to Restriction Requirement (1 Page).
- ☒ A Communication Concerning Related Applications (1 pg.).

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SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
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By: 
Atty: David R. Cochran
Reg. No. 46,632

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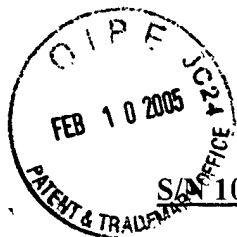


Name



Signature

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
(GENERAL)



S/N 10/722,838

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Suan J. Boon Examiner: James M. Mitchell
Serial No.: 10/722,838 Group Art Unit: 2814
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Title: METHOD OF PACKAGING AT A WAFER LEVEL

COMMUNICATION CONCERNING RELATED APPLICATION(S)

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Applicant would like to bring to the Examiner's attention the following related application(s) in the above-identified patent application:

<u>Serial/Patent No.</u>	<u>Filing Date</u>	<u>Attorney Docket</u>	<u>Title</u>
10/723474	November 26, 2003	303.601US2	ELECTRONIC APPARATUS HAVING AN ADHESIVE LAYER FROM WAFER LEVEL PACKAGING

Respectfully submitted,

SUAN J. BOON

By Applicant's Representatives,

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Date

7 February 2005

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Name

Tina Kohut

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